

AMENDMENTS TO THE CLAIMS

1. (Original) A lead frame comprising a plate-like disk part on which a chip which is a main body of an electronic component is mounted, and a plate-like lead part formed thinner than said disk part and functioning as an electrical external connecting terminal of said electronic component,

wherein said disk part and said lead part are joined together by means of ultrasonic welding.

2. (Original) The lead frame as set forth in claim 1, wherein said disk part has, on the outer periphery thereof, a projected portion and said lead part is ultrasonic welded to said projected portion.

3. (Original) The lead frame as set forth in claim 2, wherein said projected portion is thinner than a main body of said disk part.

4. (Original) The lead frame as set forth in claim 3, wherein at least a surface layer portion of said disk part is composed of copper or nickel and at least a surface layer portion of said lead part is composed of nickel or copper.

5. (Original) A lead frame comprising a plate-like disk part on which a chip which is a main body of an electronic component is mounted, and a plate-like lead part connected to said disk part and functioning as an electrical external connecting terminal of said electronic component, the whole of said lead frame being so formed as to have two portions having different thicknesses,

wherein said two portions of different thicknesses are joined together by means of ultrasonic welding.

6. (Original) A lead frame comprising a plate-like disk part on which a chip which is a main body of an electronic component is mounted, and a plate-like lead part formed thinner than said disk part and functioning as an electrical external connecting terminal of said electronic component,

wherein said disk part and said lead part are connected together by welding after caulking.

7. (First Amended) An electronic component comprising a lead frame as set forth in ~~any one of claims 1, 5, and 6~~ claim 1 and a chip which is an electronic component main body, wherein said chip is mounted on a disk part of said lead frame and said chip is electrically connected to a lead part of said lead frame.

8. (New) An electronic component comprising a lead frame as set forth in claim 5 and a chip which is an electronic component main body, wherein said chip is mounted on a disk part of said lead frame and said chip is electrically connected to a lead part of said lead frame.

9. (New) An electronic component comprising a lead frame as set forth in claim 6 and a chip which is an electronic component main body, wherein said chip is mounted on a disk part of said lead frame and said chip is electrically connected to a lead part of said lead frame.